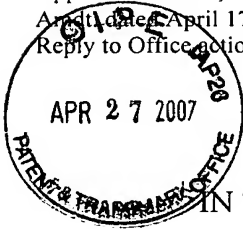


Appl. No. 10/776,477
Filed April 17, 2007
Reply to Office action of January 17, 2007

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

LLERA et al.

Application No: 10/776,477

Filed: Feb. 10, 2004

For: Method for Applying
Downward Force on Wafer During CMP
(Amended)

Group Art Unit:

Examiner: Anthony Ojini

Atty. Docket No:

Date: April 17, 2007

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on April 17, 2007.

Signed: _____

Al Penilla

AMENDMENT

Honorable Commissioner for Patents
Alexandria VA 22313-1450

Dear Sir:

In response to the Office Action dated January 17, 2007, the term to respond extends to April 17, 2007. Please enter this amendment and remarks.

Amendment to the title is reflected on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims which begin on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.

05/01/2007 FHETEKI1 00000004 500805 10776477

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TITLE

Please amend the title to:

--Method for applying downward force on a wafer during CMP--